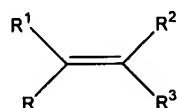


## Listing of Claims

Claims 1- 60 (Canceled)

Claim 61 (Currently amended): ~~The apparatus of claim 60, wherein the additive consumption inhibiting compound is a compound~~ An apparatus for electroplating a substrate comprising an electrical power source electrically connected with an insoluble anode and a cathode such that an electrical current can pass through the insoluble anode and the cathode, the insoluble anode and the cathode are in contact with a metal plating bath comprising a salt of a metal selected from the group consisting of copper, gold, silver, palladium, platinum, cobalt, cadmium, chromium, bismuth, indium, rhodium, iridium, and ruthenium, and an additive consumption inhibiting alcohol having a formula as follows:



wherein R, R<sup>1</sup>, R<sup>2</sup> and R<sup>3</sup> independently comprise hydrogen; -OH; hydroxy (C<sub>1</sub>-C<sub>20</sub>) linear, branched, or cyclic alkyl; hydroxy (C<sub>2</sub>-C<sub>20</sub>) linear, or branched alkenyl; hydroxy (C<sub>2</sub>-C<sub>20</sub>) linear, or branched alkynyl; hydroxy (C<sub>1</sub>-C<sub>20</sub>) linear, or branched alkoxy; hydroxyaryl; (C<sub>1</sub>-C<sub>20</sub>) linear, or branched alkyl; (C<sub>2</sub>-C<sub>20</sub>) linear, or branched alkenyl; (C<sub>2</sub>-C<sub>20</sub>) linear, or branched alkynyl; aryl; halogen; thienyl; -CN; -SCN; -C=NS; -SH; -NO<sub>2</sub>; -SO<sub>2</sub>H; -SO<sub>3</sub>M; -PO<sub>3</sub>M; -P(R<sup>4</sup>); -Si(OH)<sub>3</sub>; silyl; silane; aminyl; aminyl halide; hydroxyaminyl; keto; ester; or acyl halide; provided that at least one of R, R<sup>1</sup>, R<sup>2</sup>, or R<sup>3</sup> is -OH, hydroxy (C<sub>1</sub>-C<sub>20</sub>) alkyl, hydroxy (C<sub>2</sub>-C<sub>20</sub>) alkenyl, hydroxy (C<sub>2</sub>-C<sub>20</sub>) alkynyl, hydroxy (C<sub>1</sub>-C<sub>20</sub>) alkoxy, or hydroxyaryl; R<sup>4</sup> is hydrogen or halogen; and M is hydrogen or an alkali metal; or

~~R<sup>1</sup> and R<sup>2</sup> are taken together to form a bond; or R<sup>1</sup> and R<sup>2</sup> are taken together along with the atoms to which they are attached to form a 5 to 7 membered carbon ring; or to form a 5 to 7 membered carbon ring fused with one or more five to six membered rings carbon rings; the 5 to 7 membered rings and the one or more five to six membered rings may each contain one or more carbonyls in the ring; or the 5 to 7 membered ring or the one or more five to six membered fused rings may each contain a hetero atom to replace a carbon in the ring to form a heterocyclic ring, where oxygen or nitrogen are hetero atoms in the ring; the 5 to 7 membered rings and the five to six membered fused rings may be unsubstituted or substituted; and R and R<sup>3</sup> are as defined~~

~~above; when R<sup>1</sup> and R<sup>2</sup> are taken together to form a bond or ring structure, at least one OH group is present on the compound.~~

Claim 62 (Currently amended): The apparatus of claim 61, wherein the hydroxy (C<sub>1</sub>-C<sub>20</sub>) alkyl, hydroxy (C<sub>2</sub>-C<sub>20</sub>) alkenyl, hydroxy (C<sub>2</sub>-C<sub>20</sub>) alkynyl, hydroxy (C<sub>1</sub>-C<sub>20</sub>) alkoxy, hydroxyaryl, (C<sub>1</sub>-C<sub>20</sub>) alky, (C<sub>2</sub>-C<sub>20</sub>) alkenyl, (C<sub>2</sub>-C<sub>20</sub>) alkynyl, (C<sub>1</sub>-C<sub>20</sub>) alkoxy, or aryl, ~~the 5 to 7 membered rings, the five to six membered fused rings, and the heterocyclic rings~~ are substituted with one or more substituents comprising halogen, -OH, -CN, -SCN, -C=NS, -SH, -NO<sub>2</sub>, -SO<sub>2</sub>H, -SO<sub>3</sub>M, -PO<sub>3</sub>M, -Si(OH)<sub>3</sub>, silyl, silane, aminyl, aminylhalide, hydroxyaminyl, pentose, hexose, keto, or esters.

Claim 63 (Canceled)

Claim 64 (Currently amended): The apparatus of claim ~~60~~ 61, wherein the additive consumption inhibiting compound comprises from about 0.001 g/L to about 100.0 g/L of the bath.

Claim 65 (Currently amended): The apparatus of claim ~~60~~ 61, wherein the metal plating bath further comprises brighteners, levelers, hardeners, wetting agents, malleability modifiers, ductility modifiers, deposition modifiers, or suppressors.

Claim 66 (Currently amended): The apparatus of claim ~~60~~ 61, wherein the metal plating bath has a pH of from 0 to about 8.0.

Claim 67 (Currently amended): The apparatus of claim ~~60~~ 61, wherein the metal salt comprises copper halides, copper sulfate, copper alkane sulfonate, copper alkanol sulfonate, or mixtures thereof.

Claim 68 (Currently amended): The apparatus of claim ~~60~~ 61, wherein the insoluble anode comprises metals of cobalt, nickel, ruthenium, rhodium, palladium, iridium, or platinum.

Claim 69 (Original): The apparatus of claim 68, wherein the insoluble anode further comprises metals of titanium, zirconium, hafnium, vanadium, niobium, or tantalum.

Claim 70 (Original): The apparatus of claim 69, wherein the insoluble anode further comprises beryllium, calcium, strontium, barium, scandium, yttrium, lanthanum, or rare earth elements.

Claim 71 (Currently amended): The apparatus of claim ~~60~~ 61, wherein the insoluble anode comprises iridium dioxide.

Claim 72 (Currently amended): The apparatus of claim ~~60~~ 61, wherein the cathode comprises a wiring board, an integrated circuit, an electrical contact surface, a connector, an electrolyte foil, a

silicon wafer, a semi-conductor, a lead frame, an optoelectronic component, a solder bump, a decorative article, or a sanitary appliance, ~~and the like~~.

Claim 73 (Currently amended): The apparatus of claim ~~60~~ 61, wherein the insoluble anode and the cathode have a current density of from about 1 to about 1000 amps/ft<sup>2</sup>.